



5GHZ ÷ **4 Fixed Modulus Divider**

Preliminary Information

The SP8904 is one of a range of very high speed low power prescalers for professional applications. The dividing elements are static D type flip flops and therefore allow operation down to DC if the drive signal is a pulse waveform with fast risetime. The output stage has a differential current output and provides a direct drive into a 50 ohm load.

Ordering Information
SP8904/KG/MP1S (tubes)
SP8904/KG/MP1T (tape and reel)

Features

- Very High Operating Speed
- Operation down to DC with Square Wave Input
- Silicon Technology for Low Phase Noise (Typically better than -140dBc/Hz at 1KHz)
- 5V Single Supply Operation
- Low Power Dissipation: 350mW (Typ.)
- Surface Mount Plastic Package

Absolute Maximum Ratings

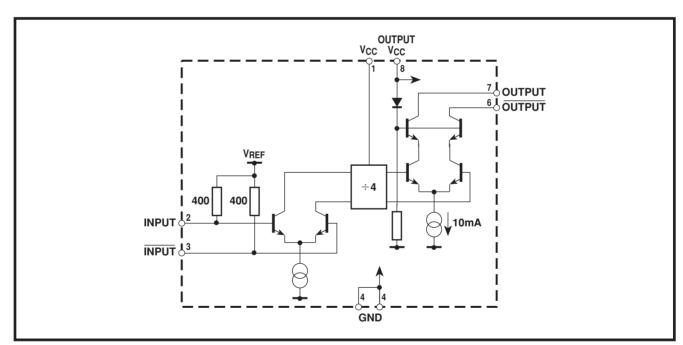


Figure 1 block diagram

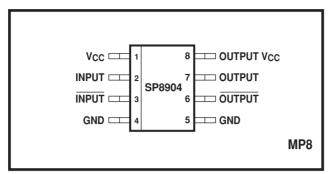


Figure 2 Pin connections - top view

Electrical Characteristics

These characteristics are guaranteed by either production test or design over the following range of operating conditions unless otherwise stated: $T_{AMB} = -40$ °C to +85°C, $V_{CC} = 4.75$ V to 5.25V

		Value					
Characteristic	Pin	Min.	Тур.	Max.	Units	Conditions	
Supply current Input frequency Input sensitivity Input sensitivity Input overload Input overload Output voltage	1, 8 2, 3 2, 3 2, 3 2, 3 2, 3 2, 3 6, 7	- 1·0 - - 440 700 -	70 - - - - - - 0.5	95 5·0 180 570 - -	mVrms mVrms mVrms Vp-p	RMS sinewave $f_{IN} = 1 \text{GHz and } 4.2 \text{GHz}$ $f_{IN} = 5 \text{GHz}$ $f_{IN} = 1 \text{GHz and } 3 \text{GHz}$ $f_{IN} = 5.0 \text{GHz and } 3.8 \text{GHz}$ Into 50Ω pullup resistor	
Output power	6, 7	-10∙0	0	+2.0	dBm	$f_{IN} = 1GHz$ and $5GHz$ (see note 1)	

NOTE

^{1.} Measured into 50Ω measuring instrument in parallel with 50Ω pullup resistor. See Figure 5.

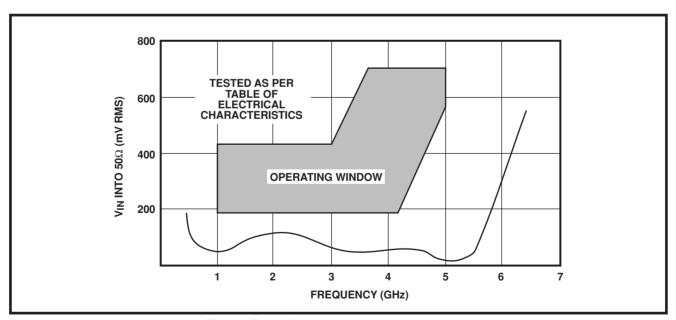


Figure3 Typical input sensitiviy (sinewave drive)

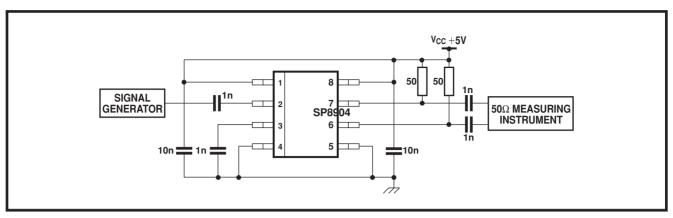


Figure 4 Typical application and test circuit

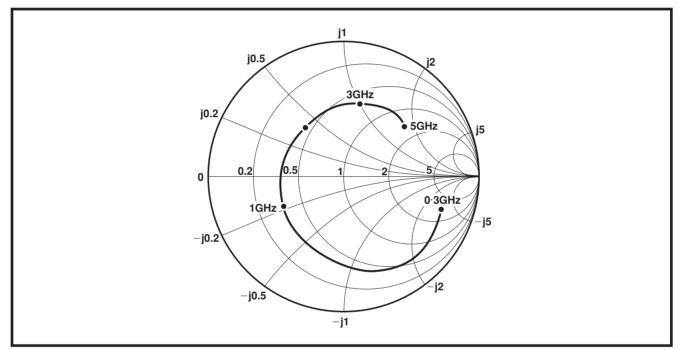


Figure 5 Typical input impedance

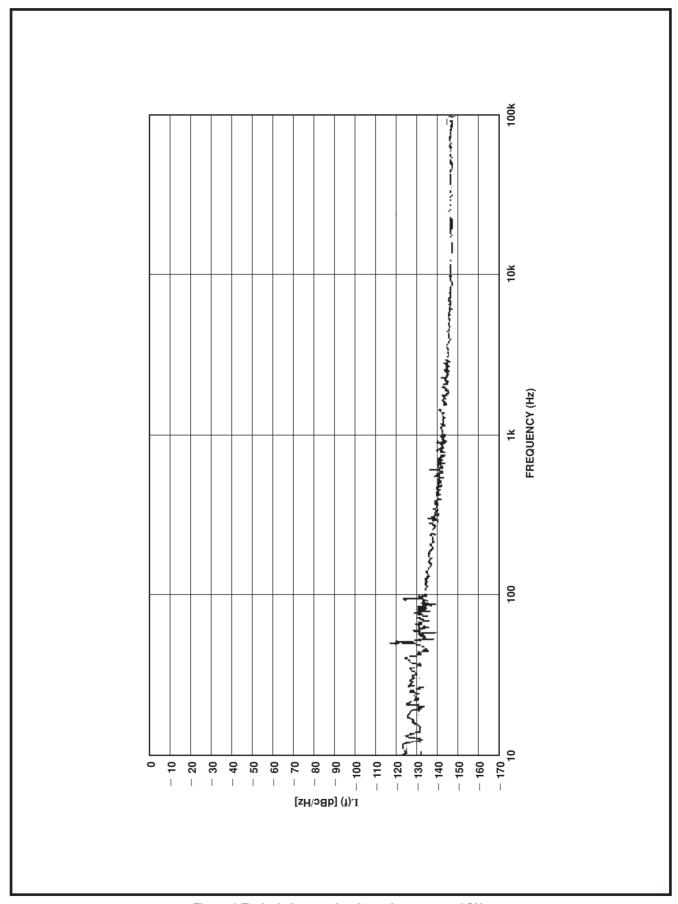
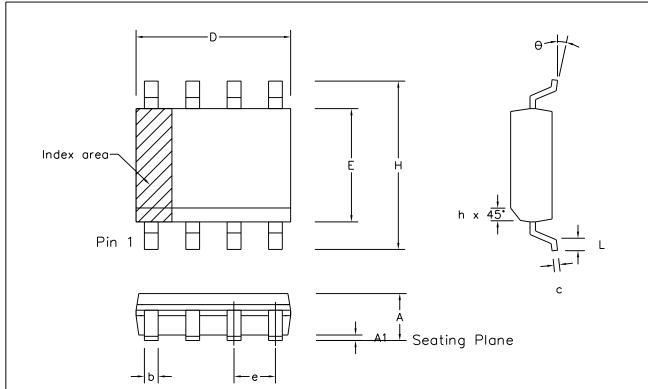


Figure 6 Typical phase noise, input frequency = 3GHz



	Min	Max	Min	Max		
	mm	mm	inch	inch		
Α	1.35	1.75	0.053	0.069		
A1	0.10	0.25	0.004	0.010		
D	4.80	5.00	0.189	0.197		
Н	5.80	6.20	0.228	0.244		
E	3.80	4.00	0.150	0.157		
L	0.40	1.27	0.016	0.050		
е	1.27	BSC	0.050 BSC			
b	0.33	0.51	0.013	0.020		
С	0.19	0.25	0.008	0.010		
0	O°	8 °	0°	8°		
h	0.25	0.50	0.010	0.020		
	Pin Features					
N	3	3	8			
Conforms to JEDEC MS-012AA Iss. C						

Notes:

- 1. The chamfer on the body is optional. If not present, a visual index feature, e.g. a dot, must be located within the cross—hatched area.
- 2. Controlling dimensions are in inches.
- 3. Dimension D do not include mould flash, protusion or gate burrs. These shall not exceed 0.006" per side.
- 4. Dimension E1 do not include inter-lead flash or protusion. These shall not exceed 0.010" per side.
- 5. Dimension b does not include dambar protusion / intrusion. Allowable dambar protusion shall be 0.004" total in excess of b dimension.

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ISSUE	1	2	3	4	5		Previous package codes	Package Outline for
ACN	6745	201936	202595	203705	212424	ZARLINK SEMICONDUCTOR		8 lead SOIC (0.150" Body width)
DATE	5Apr95	27Feb97	12Jun97	9Dec97	22Mar02		,	,
APPRD.								GPD00010



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